SPECIFICATIONS FOR NICHIA **BLUISH-GREEN** LED MODEL : **NSPE510GS**

NICHIA CORPORATION

(Ta=25°C)

1.SPECIFICATIONS

(1) Absolute Maximum Ratings			(Ta=25°C)
Item	Symbol	Absolute Maximum Rating	Unit
Forward Current	IF	30	mA
Pulse Forward Current	IFP	100	mA
Reverse Voltage	VR	5	V
Power Dissipation	Pd	120	mW
Operating Temperature	Topr	-30~+ 85	°C
Storage Temperature	Tstg	$-40 \sim +100$	°C
Soldering Temperature	Tsld	265°C for 10sec.	

IFP Conditions : Pulse Width ≤ 10 msec. and Duty $\leq 1/10$

(2) Initial Electrical/Optical Characteristics

Item		Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage		VF	IF=10[mA]	-	(3.5)	4.0	V
Reverse Current		Ir	$V_{R}=5[V]$	-	-	50	μA
Luminous Intensity	Rank ID	Iv	IF=10[mA]	1150	(2800)	-	mcd

* Luminous Intensity Measurement allowance is \pm 10%.

Color Rank		ink (IF=10mA,Ta=25°C)		
	Rank ID			
Х	0.04	0.04	0.14	0.14
У	0.39	0.65	0.65	0.39

* Color Coordinates Measurement allowance is ± 0.012 .

Average Value by Shipment Lot		(IF=10mA,Ta=25°C)	
Item	Symbol	Average Control	
Color Coordinates	X	$(\overline{x},\overline{y})$ conforms to	
(Average)	y	the ITE green color requirement.	
Luminous Intensity (Average)	Īv		

2.INITIAL OPTICAL/ELECTRICAL CHARACTERISTICS Please refer to figure's page.

3.OUTLINE DIMENSIONS AND MATERIALS

Please refer to figure's page.

Material as follows ;	Resin(Mold)	:	Epoxy Resin	1
	Leadframe	:	Ag plating	Copper Alloy

4.PACKAGING

 \cdot The BG-LEDs are packed in cardboard boxes after packaging in anti-electrostatic bags. Please refer to figure's page.

The label on the minimum packing unit shows ; Part Number, Lot Number, Ranking, Quantity

- \cdot In order to protect the BG-LEDs from mechanical shock, we pack them in cardboard boxes for transportation.
- \cdot The BG-LEDs may be damaged if the boxes are dropped or receive a strong impact against them, so precautions must be taken to prevent any damage.
- The boxes are not water resistant and therefore must be kept away from water and moisture.
- · When the BG-LEDs are transported, we recommend that you use the same packing method as Nichia.

5.LOT NUMBER

The first six digits number shows lot number.

The lot number is composed of the following characters;

 $\bigcirc \Box \times \times \times \times \text{ - } \bigtriangleup \blacksquare$

○ - Year (6 for 2006, 7 for 2007)

- \Box Month (1 for Jan., 9 for Sep., A for Oct., B for Nov.)
- $\times \times \times \times$ Nichia's Product Number
 - \triangle Ranking

6.RELIABILITY (1) TEST ITEMS AND RESULTS

	Standard			Number of
Test Item	Test Method	Test Conditions	Note	Damaged
Resistance to	JEITA ED-4701	Tsld= $260 \pm 5^{\circ}$ C, 10sec.	1 time	0/50
Soldering Heat	300 302	3mm from the base of the epoxy bulb		
Solderability	JEITA ED-4701	Tsld= $235 \pm 5^{\circ}$ C, 5sec.	1 time	0/50
	300 303	(using flux)	over 95%	
Temperature Cycle	JEITA ED-4701	$-40^{\circ}\mathrm{C}\sim25^{\circ}\mathrm{C}\sim100^{\circ}\mathrm{C}\sim25^{\circ}\mathrm{C}$	100 cycles	0/50
	100 105	30min. 5min. 30min. 5min.		
Moisture Resistance Cyclic	JEITA ED-4701	$25^{\circ}C \sim 65^{\circ}C \sim -10^{\circ}C$	10 cycles	0/50
	200 203	90%RH 24hrs./1cycle	-	
Terminal Strength	JEITA ED-4701	Load 5N (0.5kgf)	Nonoticeable	0/50
(bending test)	400 401	$0^{\circ} \sim 90^{\circ} \sim 0^{\circ}$ bend 2 times	damage	
Terminal Strength	JEITA ED-4701	Load 10N (1kgf)	No noticeable	0/50
(pull test)	400 401	10 ± 1 sec.	damage	
High Temperature Storage	JEITA ED-4701	Ta=100°C	1000hrs.	0/50
	200 201			
Temperature Humidity	JEITA ED-4701	Ta=60°C, RH=90%	1000hrs.	0/50
Storage	100 103			
Low Temperature Storage	JEITA ED-4701	Ta=-40°C	1000hrs.	0/50
	200 202			
Steady State Operating Life		Ta=25°C, IF=30mA	1000hrs.	0/50
Steady State Operating Life		60°C, RH=90%, IF=20mA	500hrs.	0/50
of High Humidity Heat				
Steady State Operating Life		Ta=-30°C, IF=20mA	1000hrs.	0/50
of Low Temperature		-, -		

(2) CRITERIA FOR JUDGING DAMAGE

			Criteria for Judgement	
Item	Symbol	Test Conditions	Min.	Max.
Forward Voltage	VF	IF=10mA	-	U.S.L.*)× 1.1
Reverse Current	Ir	V _R =5V	-	U.S.L.*) \times 2.0
Luminous Intensity	Iv	IF=10mA	L.S.L.**)× 0.7	-

*) U.S.L.: Upper Standard Level **) L.S.L.: Lower Standard Level

7.CAUTIONS

(1) Lead Forming

 \cdot When forming leads, the leads should be bent at a point at least 3mm from the base of the epoxy bulb. Do not use the base of the leadframe as a fulcrum during lead forming.

- \cdot Lead forming should be done before soldering.
- \cdot Do not apply any bending stress to the base of the lead. The stress to the base may damage the BG-LED's characteristics or it may break the BG-LEDs.
- When mounting the BG-LEDs onto a printed circuit board, the holes on the circuit board should be exactly aligned with the leads of the BG-LEDs. If the BG-LEDs are mounted with stress at the leads, it causes deterioration of the epoxy resin and this will degrade the BG-LEDs.

(2) Storage

- The BG-LEDs should be stored at 30°C or less and 70%RH or less after being shipped from Nichia and the storage life limits are 3 months. If the BG-LEDs are stored for 3 months or more, they can be stored for a year in a sealed container with a nitrogen atmosphere and moisture absorbent material.
- Nichia BG-LED leadframes are silver plated copper alloy. The silver surface may be affected by environments which contain corrosive substances. Please avoid conditions which may cause the BG-LED to corrode, tarnish or discolor. This corrosion or discoloration may cause difficulty during soldering operations. It is recommended that the BG-LEDs be used as soon as possible.
- Please avoid rapid transitions in ambient temperature, especially, in high humidity environments where condensation can occur.

(3) Static Electricity

 \cdot Static electricity or surge voltage damages the BG-LEDs.

It is recommended that a wrist band or an anti-electrostatic glove be used when handling the BG-LEDs. • All devices, equipment and machinery must be properly grounded. It is recommended that precautions be taken against surge voltage to the equipment that mounts the BG-LEDs.

- When inspecting the final products in which BG-LEDs were assembled, it is recommended to check whether the assembled BG-LEDs are damaged by static electricity or not. It is easy to find static-damaged BG-LEDs by a light-on test or a VF test at a lower current (below 1mA is recommended).
- Damaged BG-LEDs will show some unusual characteristics such as the leak current remarkably increases, the forward voltage becomes lower, or the BG-LEDs do not light at the low current.

Criteria : (VF > 2.0V at IF=0.5mA)

(4) Soldering Conditions

- Nichia BG-LED leadframes are silver plated copper alloy. This substance has a low
- thermal coefficient (easily conducts heat). Careful attention should be paid during soldering.

• Solder the BG-LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.

· Recommended soldering conditions

Dip Soldering		Hand Soldering		
Pre-Heat	120°C Max.	Temperature	350°C Max.	
Pre-Heat Time	60 seconds Max.	Soldering Time	3 seconds Max.	
Solder Bath	260°C Max.	Position	No closer than 3 mm from the	
Temperature			base of the epoxy bulb.	
Dipping Time	10 seconds Max.			
Dipping Position	No lower than 3 mm from the			
	base of the epoxy bulb.			

- Although the recommended soldering conditions are specified in the above table, dip or hand soldering at the lowest possible temperature is desirable for the BG-LEDs.
- · A rapid-rate process is not recommended for cooling the BG-LEDs down from the peak temperature.
- \cdot Dip soldering should not be done more than one time.
- \cdot Hand soldering should not be done more than one time.
- \cdot Do not apply any stress to the lead particularly when heated.
- The BG-LEDs must not be repositioned after soldering.
- \cdot After soldering the BG-LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the BG-LEDs return to room temperature.
- Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused from warping of the PC board or from the clinching and cutting of the leadframes. When it is absolutely necessary, the BG-LEDs may be mounted in this fashion but the User will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur. Nichia's BG-LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.
- \cdot When it is necessary to clamp the BG-LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the BG-LEDs.
- Cut the BG-LED leadframes at room temperature. Cutting the leadframes at high temperatures may cause failure of the BG-LEDs.

(5) Heat Generation

• Thermal design of the end product is of paramount importance. Please consider the heat generation of the BG-LED when making the system design. The coefficient of temperature increase per input electric power is affected by the thermal resistance of the circuit board and density of BG-LED placement on the board, as well as other components. It is necessary to avoid intense heat generation and operate within the maximum ratings given in this specification.

 \cdot The operating current should be decided after considering the ambient maximum temperature of BG-LEDs.

(6) Cleaning

- It is recommended that isopropyl alcohol be used as a solvent for cleaning the BG-LEDs. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the resin or not. Freon solvents should not be used to clean the BG-LEDs because of worldwide regulations.
- Do not clean the BG-LEDs by the ultrasonic. When it is absolutely necessary, the influence of ultrasonic cleaning on the BG-LEDs depends on factors such as ultrasonic power and the assembled condition. Before cleaning, a pre-test should be done to confirm whether any damage to the BG-LEDs will occur.

(7) Safety Guideline for Human Eyes

In 1993, the International Electric Committee (IEC) issued a standard concerning laser product safety (IEC 825-1). Since then, this standard has been applied for diffused light sources (BG-LEDs) as well as lasers. In 1998 IEC 60825-1 Edition 1.1 evaluated the magnitude of the light source.
In 2001 IEC 60825-1 Amendment 2 converted the laser class into 7 classes for end products. Components are excluded from this system. Products which contain visible BG-LEDs are now classified as class 1. Products containing UV LEDs are class 1M. Products containing BG-LEDs can be classified as class 2 in cases where viewing angles are narrow, optical manipulation intensifies the light, and/or the energy emitted is high. For these systems it is recommended to avoid long term exposure. It is also recommended to follow the IEC regulations regarding safety and labeling of products.

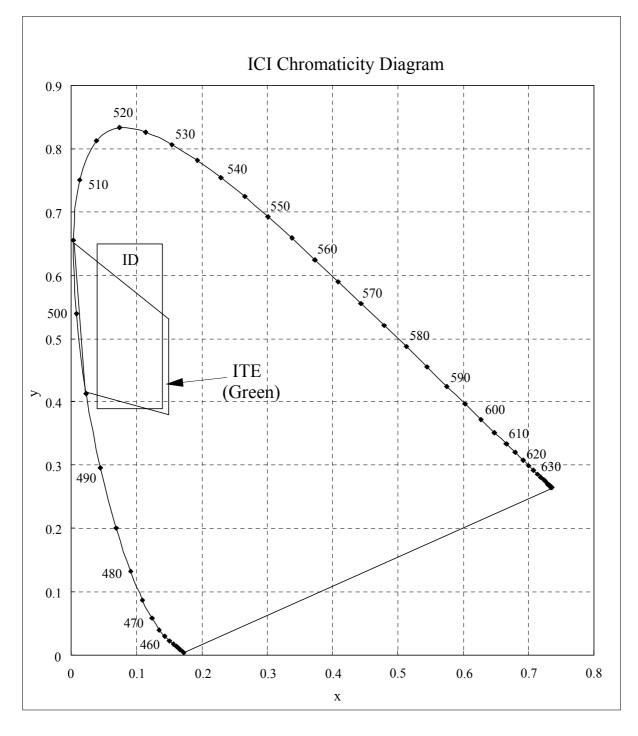
(8) Others

· NSPE510GS complies with RoHS Directive.

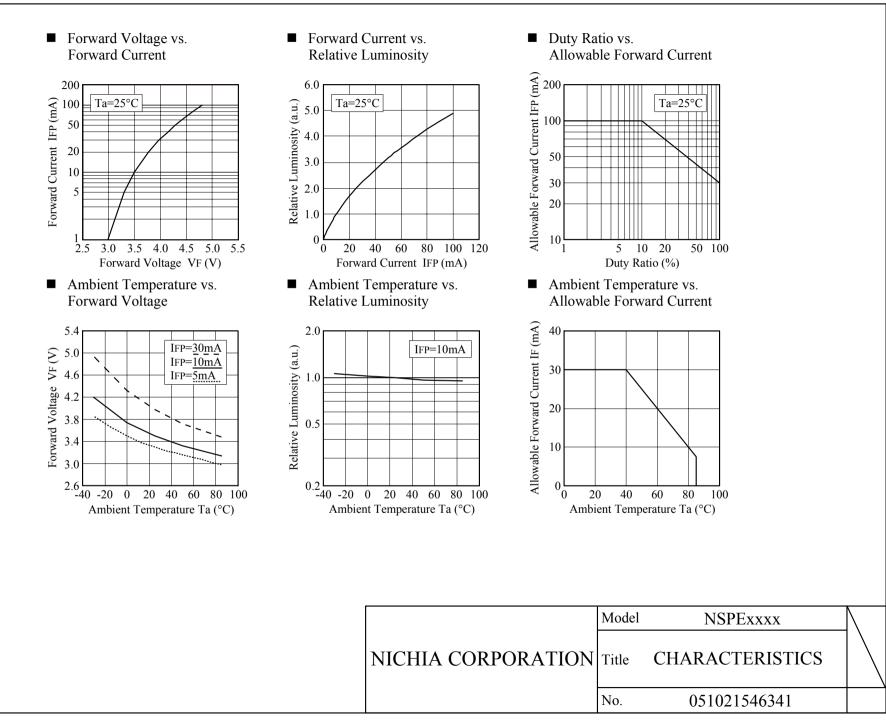
- If the BG-LEDs are being used after being fixed into a case (container, box, etc...) the BG-LEDs must not be mounted so that the epoxy lens is pressed or glued onto a plastic (or metal) board.
- Flashing lights have been known to cause discomfort in people; you can prevent this by taking precautions during use. Also, people should be cautious when using equipment that has had BG-LEDs incorporated into it.
- These BG-LEDs are designed and manufactured for standard applications of traffic signals. It is recommended to consult with Nichia in advance if these BG-LEDs are used for other applications.
- User shall not reverse engineer by disassembling or analysis of the BG-LEDs without having prior written consent from Nichia. When defective BG-LEDs are found, the User shall inform Nichia directly before disassembling or analysis.

 \cdot The formal specifications must be exchanged and signed by both parties before large volume purchase begins.

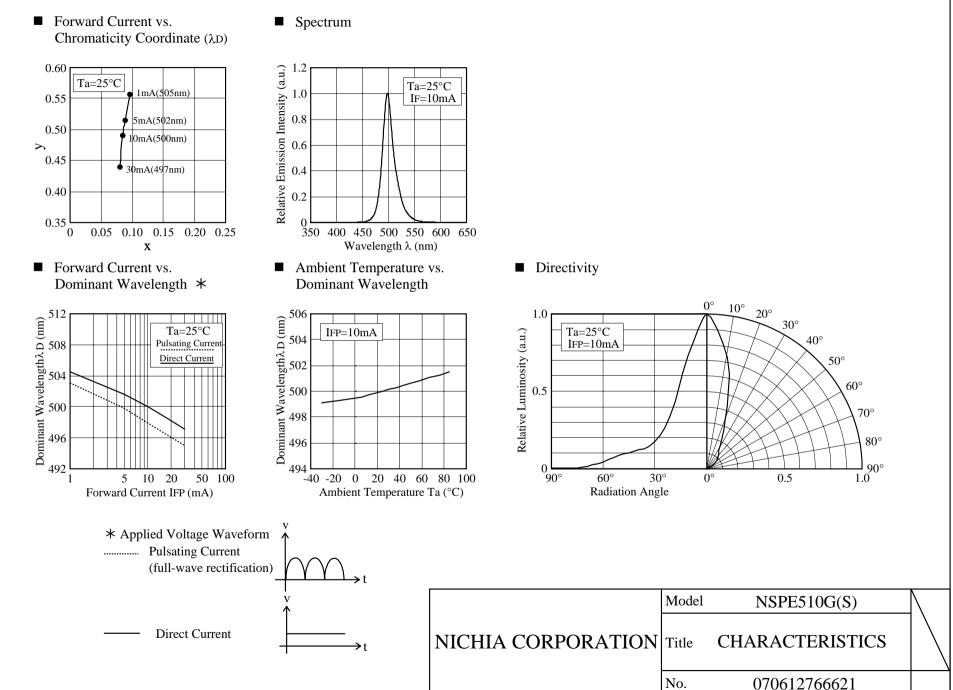
• The appearance and specifications of the product may be modified for improvement without notice.



* Color Coordinates Measurement allowance is ± 0.012 .



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